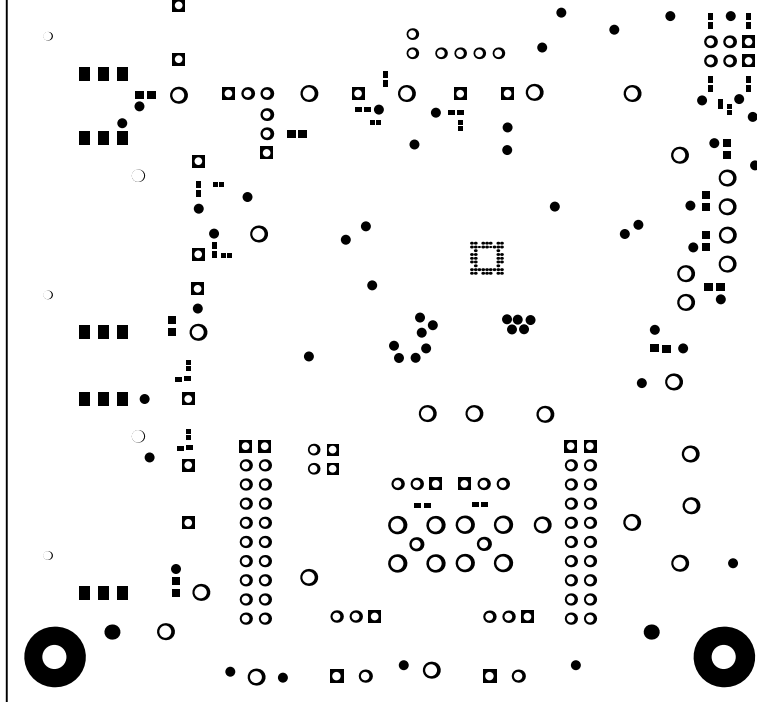


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: HUL084	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 5/16/2014 1:14:27 PM	TEXAS INSTRUMENTS	

ersionControl

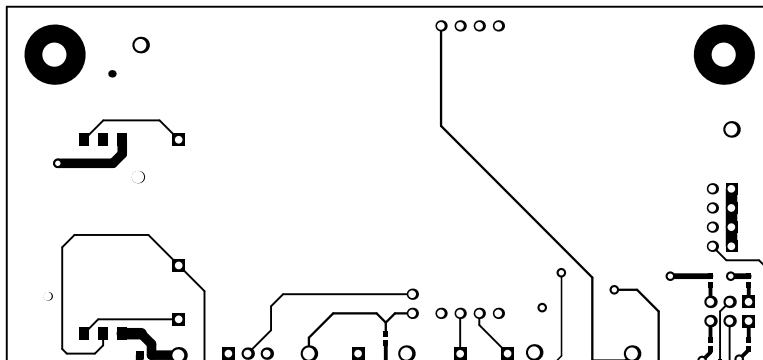
INSTRUMENTS

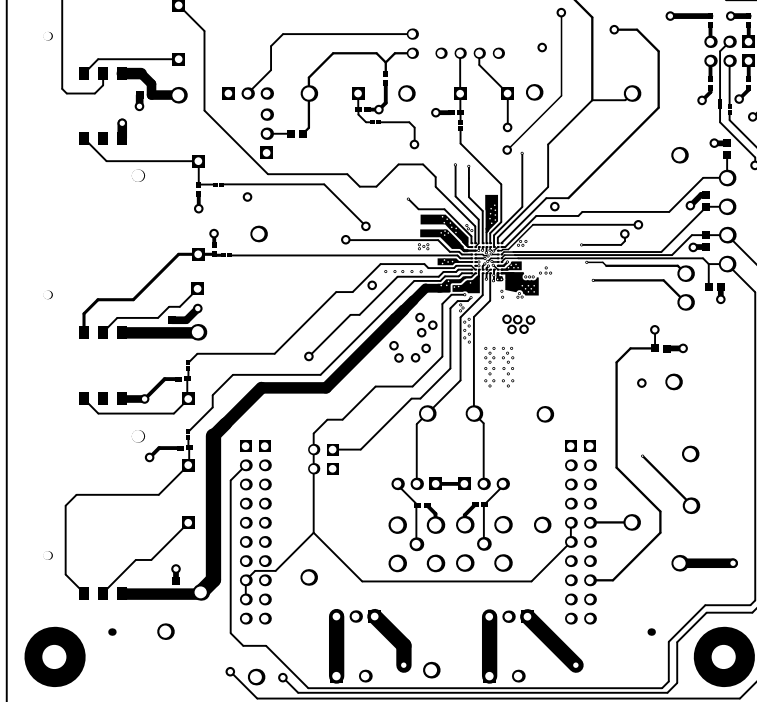


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: HVL084	REV: A	SUN REV: Not In VersionCont
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 5/16/2014 1:14:34 PM	TEXAS INSTRUMENT	

ersionControl

INSTRUMENTS

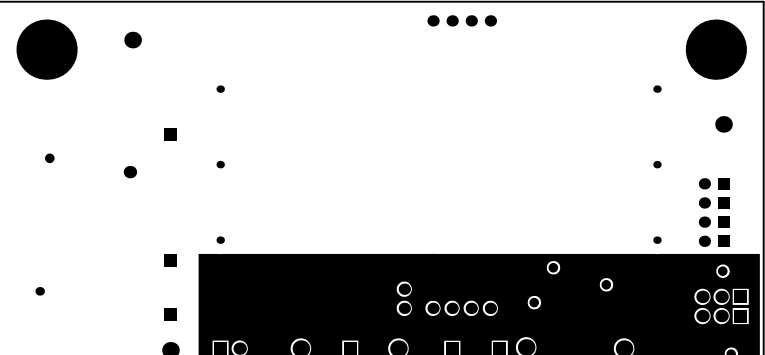


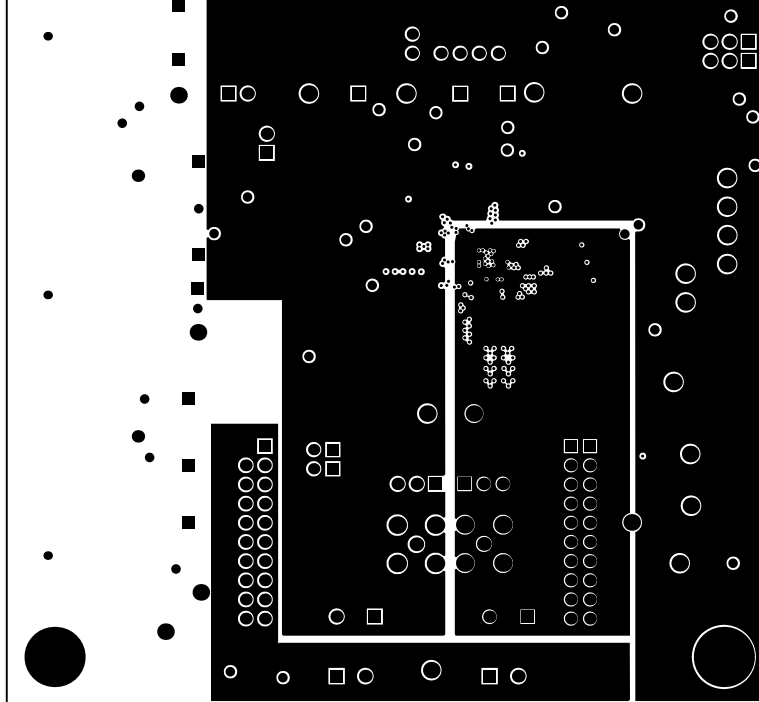


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: HVL084	REV: A	SUN REV: Not In VersionCont
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 5/16/2014 1:14:41 PM	TEXAS INSTRUMENT	

ersionControl

INSTRUMENTS



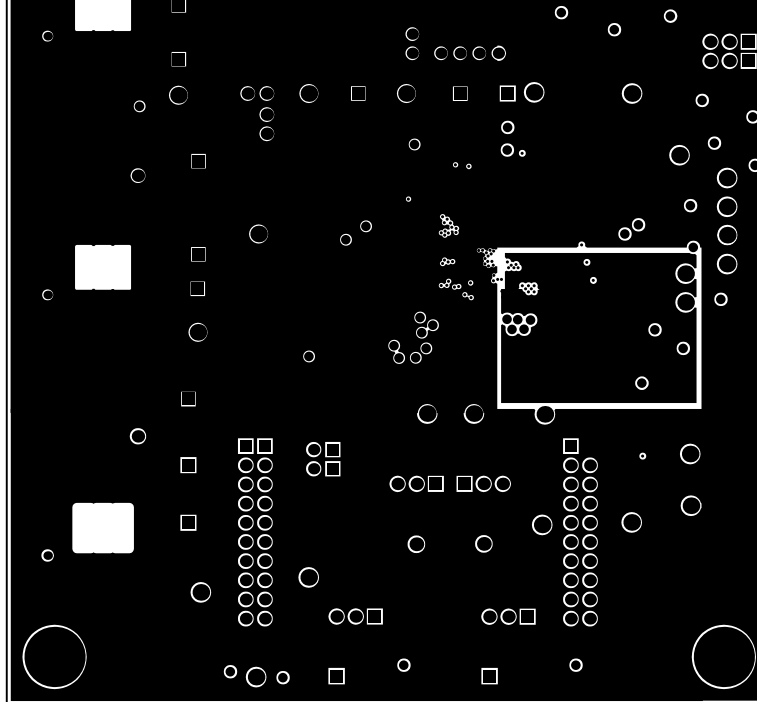


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: HVL084	REV: A	SUN REV: Not In VersionCont
LAYER NAME = VDD/VDDINTF#3			
PLOT NAME = VDD - Internal 1	GENERATED : 5/16/2014 1:14:48 PM	TEXAS INSTRUMENT	

ersionControl

INSTRUMENTS

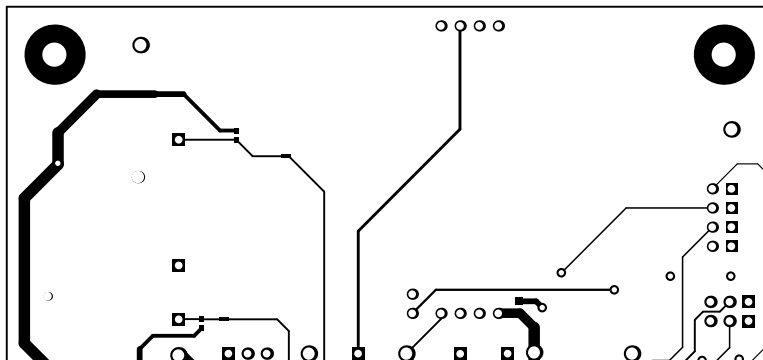


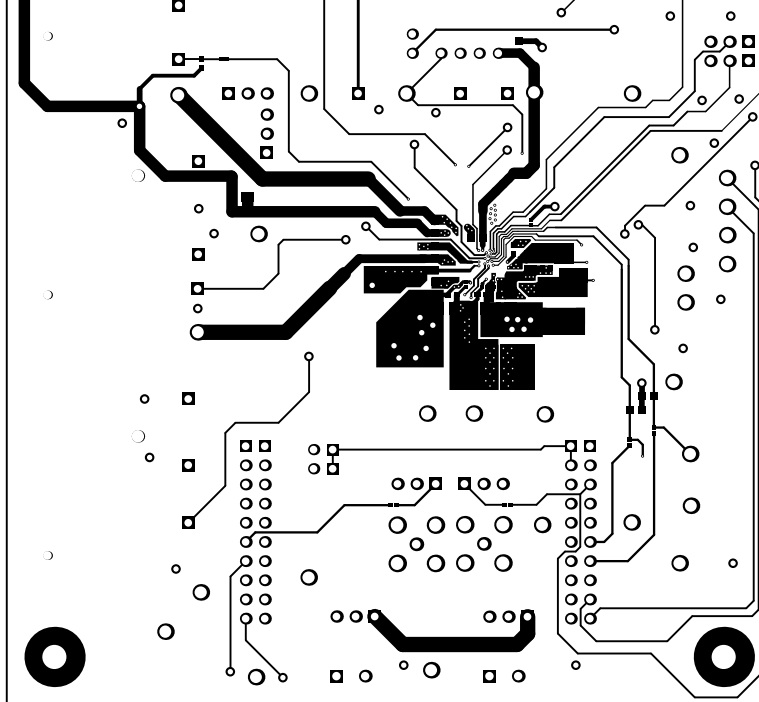


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: HVL084	REV: A	SUN REV: Not In VersionCont
LAYER NAME = GND#4			
PLOT NAME = GND - Internal 2	GENERATED : 5/16/2014 1:14:55 PM	TEXAS INSTRUMENT	

ersionControl

INSTRUMENTS

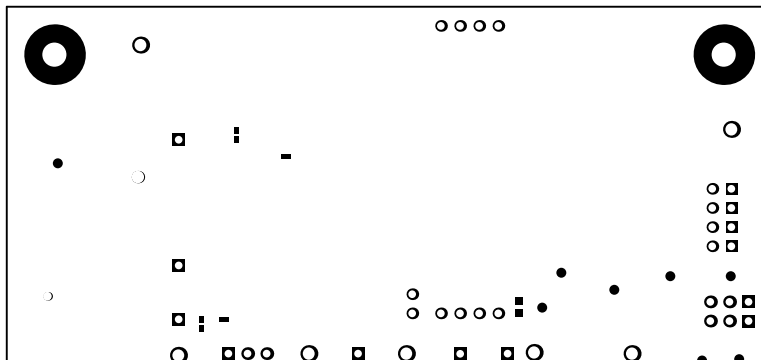


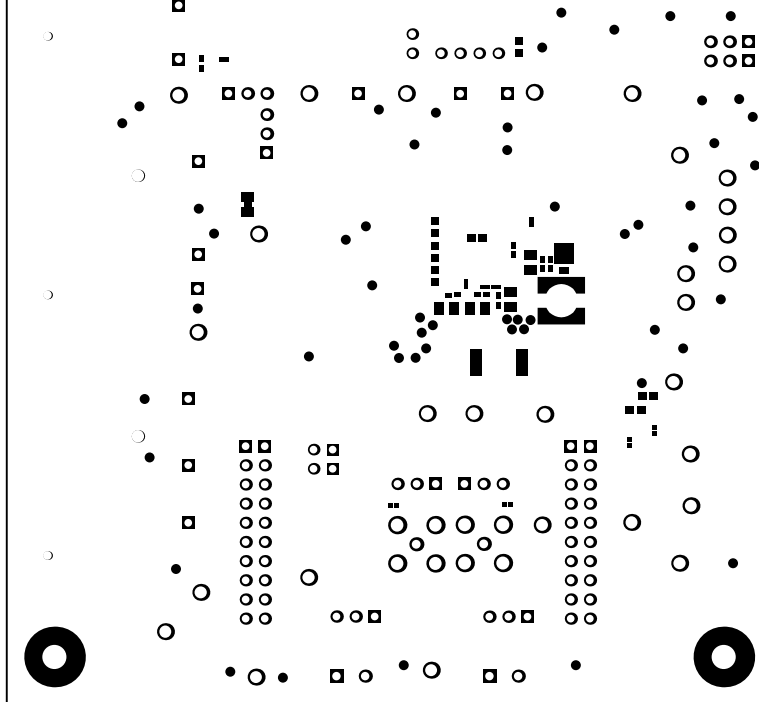


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: HVL084	REV: A	SUN REV: Not In VersionCont
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 5/16/2014 1:15:01 PM	TEXAS INSTRUMENT	

ersionControl

INSTRUMENTS





ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: HVL084	REV: A	SUN REV: Not In VersionCont
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 5/16/2014 1:15:09 PM	TEXAS INSTRUMENT	

ersionControl

INSTRUMENTS

L JCS

R14

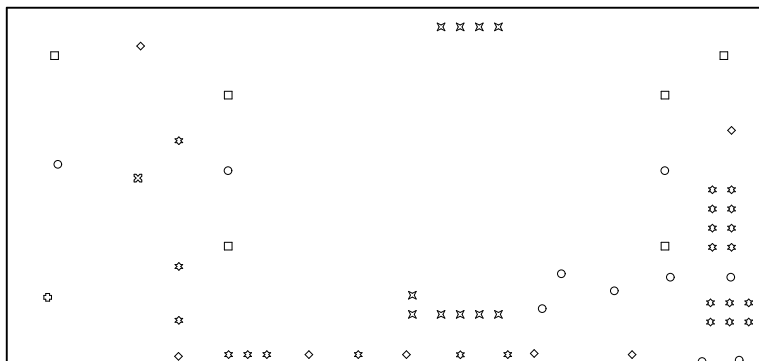
SC17

R12

SC17

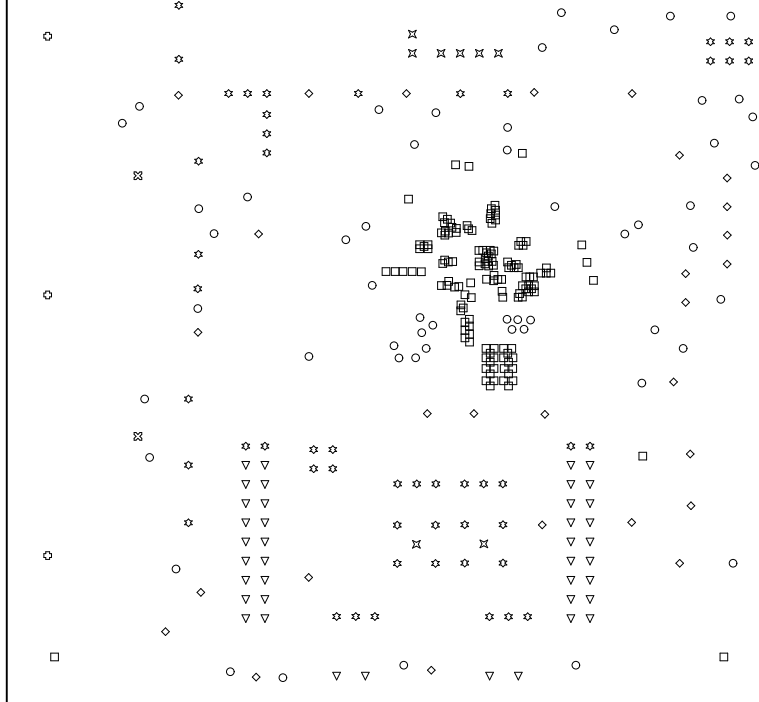
ersionControl

INSTRUMENTS



Symbol	Hit Count	Tool Size	Plated	Hole Type
□	135	8mil (0.203mm)	PTH	Round
○	55	28mil (0.711mm)	PTH	Round
×	10	39.37mil (1mm)	PTH	Round
✱	52	40mil (1.016mm)	PTH	Round
▽	36	40.157mil (1.02mm)	PTH	Round
∇	4	43.307mil (1.1mm)	PTH	Round
⊕	3	45mil (1.143mm)	NPTH	Round
⊗	2	46mil (1.168mm)	PTH	Round
◇	30	63mil (1.6mm)	PTH	Round
⊗	3	65mil (1.651mm)	NPTH	Round
✱	8	67mil (1.702mm)	PTH	Round
○	2	86.614mil (2.2mm)	PTH	Round
□	8	125.984mil (3.2mm)	PTH	Round
	348 Total			

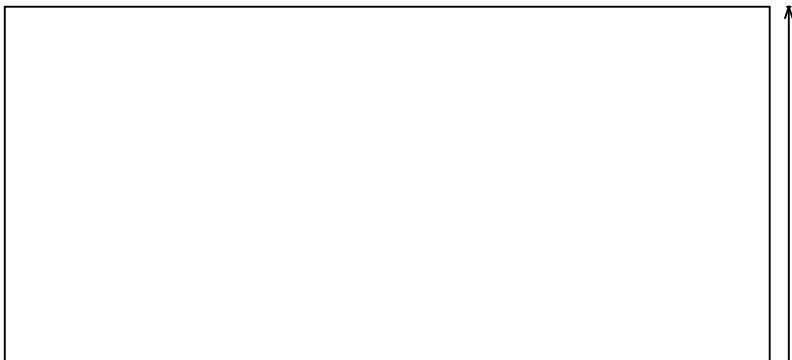
Drill Table



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: HUL084	REV: A	SUN REV: Not In VersionCont
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 5/16/2014 1:15:23 PM	TEXAS INSTRUMENT	

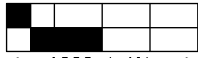
ersionControl

INSTRUMENTS





← 4000 (mil) →



← 1000 (mil) →

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: HVL084	REV: A	SUN REV: Not In VersionCont
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 5/16/2014 1:15:30 PM	TEXAS INSTRUMENT	

ersionControl

INSTRUMENTS

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